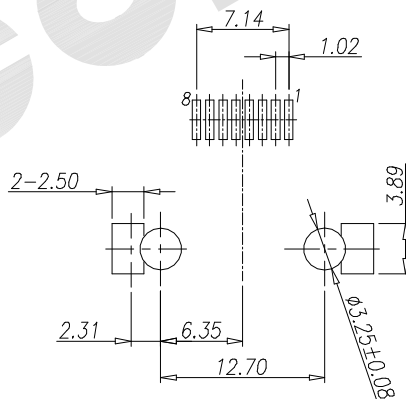
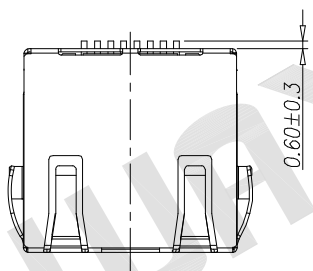
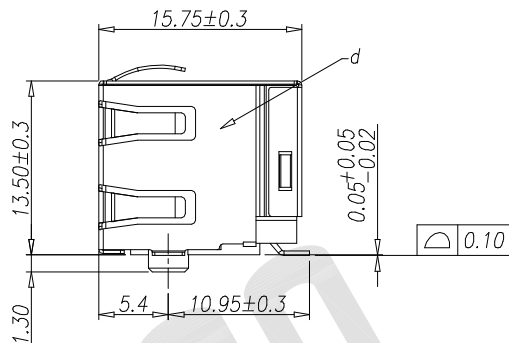
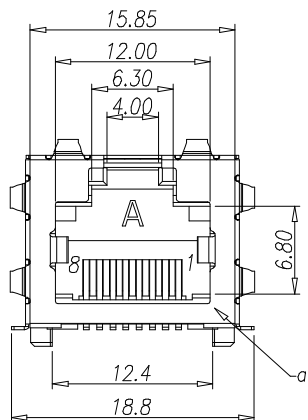
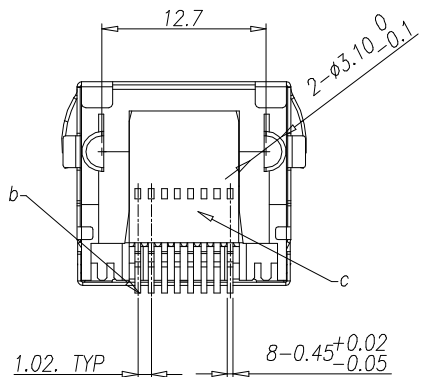


REV.	DESCRIPTION	DRAWN	CHECKED	APPROVED
A	NEW RELEASE	JLZ 03/24/16'	~	



RECOMMEND PCB LAYOUT
 PCB THICKNESS:1.60mm.
 Jack Top View
 PCB LAYOUT TOLERANCE:±0.05mm.



Description:

Shielded RJ45 SMT Modular Jack with EMI, w/o LED, 90°

Material:

Housing Material: High Temp Nylon, LCP, PA9T, UL94V-0
 Contact Material: Phosphor Bronze T-0.35mm Thickness
 Plating: Selective Gold Plating on Contact Area
 Gold Plating Thickness: (Au 1u", 3u", 6u", 15u", 30u", 50u")
 100u" Min. Matte Tin Plated on Soldering Area
 50u" Min. Nickel Plated Overall
 Shell: Copper Alloy, 0.25mm Thickness

Electrical:

Voltage Rating: 125 V AC RMS
 Current Rating: 1.5 Amp
 Contact Resistance: 30mΩ Max.
 Insulation Resistance: 500MΩ Min. @ 500 VDC
 Dielectric Withstanding Resistance: 1000 VAC RMS 50Hz, 1 Min.

Mechanical:

Durability : 750 Cycles Min.

Environmental:

Storage Temperature : -40°C to +85°C
 Operation Temperature: -40°C to +85°C
 Reflow Soldering Temperature : 255°C to 265°C, 5-10 seconds

MJ5611SE - X X X X X X

No. of Positions	Positions Loaded	LED	Insulator Material	Contact Plating	Packing Style
4,6,8	2,4,6,8	0 - Without 1 - G/Y 2 - Y/G 3 - Other	1 - PBT 2 - PA66 3 - PA46 4 - LCP 5 - PA9T	1 - 1μ" 2 - 3μ" 3 - 6μ" 4 - 15μ" 5 - 30μ"	1 - Tape & Reel 2 - Plastic Tray

GENERAL TOLERANCE	ANGLE TOLERANCE	PROJECTION	TITLE	Shielded RJ45 SMT Modular Jack with
X. ±0.60	X. ±5°	mm		EMI, w/o LED, 90°
.X ±0.38	.X ±3°		SHEET SIZE	A4
.XX ±0.25	.XX ±2°		SERIES	SMT SERIES
DRAWING TYPE	CUSTOMER	WAYCONN CO.,LTD		
SCALE	1:1 SHEET 1 OF 1			
DRAWING NO.	MJ5611SE-XXXXXX			